

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S30	2	("6777677").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/10 16:30
S31	4700	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 16:36
S32	117	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 16:37
S33	74038	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with size or location with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 16:38
S34	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with size with location with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 16:38
S35	2	"20050049836"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 16:39
S36	117	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 16:56

S37	2	("6888674").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/10 17:04
S38	119	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:09
S39	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (analyz\$3 or analys\$3 or diagnos\$3) with auger	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:15
S40	17	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (analyz\$3 or analys\$3 or diagnos\$3) with (state or status or condition)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:17
S41	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and chemical\$4 with (analyz\$3 or analys\$3 or diagnos\$3) with (state or status or condition)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:17
S42	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (analyz\$3 or analys\$3 or diagnos\$3) with (state or status or condition) and phase with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:18
S43	7	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (analyz\$3 or analys\$3 or diagnos\$3) with (scan or delayer or depth)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:18
S44	16	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (analyz\$3 or analys\$3 or diagnos\$3) with (mapping or match\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:21

S45	5	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (analyz\$3 or analys\$3 or diagnos\$3) with (mapping or match\$3) and compar\$4 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:22
S46	5	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (analyz\$3 or analys\$3 or diagnos\$3) with (mapping or match\$3) and compar\$4 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:23
S47	4	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (analyz\$3 or analys\$3 or diagnos\$3) with (mapping or match\$3) and compar\$4 with (predetermined or preset\$4 or predefined or reference or desired or expected or threshold or basic or histor\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:24
S48	4	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$5) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (analyz\$3 or analys\$3 or diagnos\$3) with (mapping or match\$3) and compar\$4 with (predetermined or preset\$4 or predefined or reference or desired or expected or threshold or basic or histor\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:25
S49	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:28

S50	14	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:29
S51	2	("6777674").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/10 17:34
S52	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and ".mu.m"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:39
S53	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and ".mu.m"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:40
S54	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and ".mu.m"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:40
S55	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and single with phase with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:42
S56	44	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and phase with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 17:43

S57	1213	702/117.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 18:12
S58	426	702/58.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 10:26
S59	5	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (adjust\$4 or correct\$4 or compensat\$4 or modif\$5 or calibrat\$4) with process\$3 with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 11:53
S60	11	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (adjust\$4 or correct\$4 or compensat\$4 or modif\$5 or calibrat\$4) with process\$3 with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 11:58
S61	6	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (adjust\$4 or correct\$4 or compensat\$4 or modif\$5 or calibrat\$4) with process\$3 with (die or semiconductor or wafer or chip or IC or integrated adj circuit) not S59	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 12:00
S62	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and focus with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:34

S63	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and focus with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:34
S64	8	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and focus\$3 with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:35
S65	0	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and focus\$3 with ion with beam same cross-section	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:36
S66	0	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and ion with beam same cross-section	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:36
S67	0	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with size with location with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and ion with beam same (cross\$3 with section or cross-section)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:37
S68	27	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (size or location) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and focus\$3 with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:38
S69	5	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (size or location) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and focus\$3 with ion with beam same (cross\$3 with section or cross-section)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:38

S70	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (size or location) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and scan\$4 with auger with microscopy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:49
S71	3	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root and scan\$4 with auger with microscopy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:50
S72	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (semiconductor or chip or wafer or IC or integrated adj circuit) and scan\$4 with auger with microscopy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:53
S73	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root same (semiconductor or chip or wafer or IC or integrated adj circuit) and scan\$4 with auger with microscopy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:53
S74	6	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root same (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan\$4 with auger with microscopy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 13:54
S75	58	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan\$4 with auger with microscopy) and focus\$3 with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:03
S76	8	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan\$4 with auger with microscopy) and cut\$4 with focus\$3 with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:04
S77	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan\$4 with auger with microscopy) and cut\$4 with focus\$3 with ion with beam same (cross\$3 with section or cross-section)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:04

S78	3	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan \$4 with auger with microscopy or energy with dispersive with spectrometer) and cut\$4 with focus\$3 with ion with beam same (cross\$3 with section or cross-section)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:09
S79	34	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified) with (defect or fail \$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:21
S80	12	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified) with (defect or fail \$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with process	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:22
S81	9	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified) with (defect or fail \$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:23
S82	14	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified) with (defect or fail \$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:23
S84	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type not S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:31

S85	6	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type not S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:32
S86	2312	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type not S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:33
S87	1544	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type not S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:34
S88	1332	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:34
S89	24	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type not S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 14:35
S92	38	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:02

S93	33	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:10
S94	15	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:26
S95	123	"5991699".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:29
S96	26	"5991699".uref. and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:29
S97	0	"5991699".uref. and (class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type and (point with scan or delayer or depth with profile) with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:34
S98	1	(class or classification or categor\$6 or classify\$3 or classified or table) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point with scan or delayer or depth with profile) with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:35
S99	51	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point with scan or delayer or depth with profile) with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:36

S100	17	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point with scan or delayer or depth with profile) with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:37
S101	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point adj scan or delayer or depth adj profile) same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:39
S102	5	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point adj scan or delayer or depth adj profile) same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:43
S103	82	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point adj scan or delayer or depth adj profile) same chemical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:43
S104	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and point adj scan with delayer with depth adj profile same chemical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:44
S105	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and point adj scan with delayer with depth adj profile same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:45
S106	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and point adj scan with delayer with depth adj profile same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:46
S107	1	point adj scan with delayer with depth adj profile same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:46

S109	2	point adj scan same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:47
S110	1	delayer same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:47
S111	128	depth with profile same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:47
S112	49	depth with profile with chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:48
S113	1	depth with profile with chemical with analysis with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:48
S114	0	point with scan\$4 with chemical with analysis with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:50
S115	0	point with scan\$4 with chemical with analysis same (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:51
S116	7	point with scan\$4 with chemical with analysis and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:51

S117	1	point adj scan with delayer with depth adj profile	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:56
S118	2	point adj scan with depth adj profile	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 15:56
S119	751	point with scan\$4 with analysis and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:03
S120	4	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and point with scan\$4 with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:03
S121	2	("6734427").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/11 16:07
S122	3	energy with dispers\$4 with spectrometer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:11
S123	1163	energy with dispers\$4 with spectrometer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:11
S124	1	energy with dispers\$4 with spectrometer with thick with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:12

S125	1	energy with dispers\$4 with spectrometer same thick with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:12
S127	0	energy with dispers\$4 with spectrometer with size same (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:13
S128	19	energy with dispers\$4 with spectrometer with size	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:14
S129	64	(EDS or energy with dispers\$4 with spectrometer) with (analyz\$3 or analys\$3) with microscop\$4 with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:20
S130	1	energy with dispers\$4 with spectrometer with thick with particle and cut \$4 with (FIB or focus with ion wiht beam) with (cross-section or cross\$3 wiht section)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:21
S131	1	energy with dispers\$4 with spectrometer with thick with particle and (FIB or focus with ion wiht beam) with (cross-section or cross\$3 wiht section)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:22
S132	7	(EDS or energy with dispers\$4 with spectrometer) with (analyz\$3 or analys\$3) with microscop\$4 with particle and auger with (analys\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 16:23
S133	3	((("6744266") or ("5985680") or ("5991699"))).PN.	USPAT	OR	OFF	2008/06/11 16:28
S134	5	((("6744266") or ("6734277") or ("5985680") or ("5991699") or ("5561293"))).PN.	USPAT	OR	OFF	2008/06/11 16:30

S135	28	(US-20050049836-\$ or US-20080129988-\$ or US-20080115029-\$ or US-20080081385-\$ or US-20050004774-\$ or US-20020196969-\$ or US-20040252879-\$ or US-20050159909-\$ or US-20050177264-\$ or US-20050080572-\$ or US-20040122859-\$).did. or (US-6516433-\$ or US-7337034-\$ or US-6466895-\$ or US-6407386-\$ or US-6392434-\$ or US-5787190-\$ or US-6971054-\$ or US-6777677-\$ or US-5985680-\$ or US-5991699-\$ or US-7020536-\$ or US-7071011-\$ or US-7359544-\$ or US-6744266-\$ or US-6734277-\$ or US-5561293-\$).did. or (US-6516433-B-\$ or US-5972728-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2008/06/11 16:31
S136	5	(("6744266") or ("6734477") or ("5985680") or ("5991699") or ("5561293")).PN.	USPAT	OR	OFF	2008/06/11 17:34
S137	5	(("6744266") or ("6734427") or ("5985680") or ("5991699") or ("5561293")).PN.	USPAT	OR	OFF	2008/06/11 17:34
S138	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 17:58
S139	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 17:58
S140	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer same (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 17:59
S141	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:00
S142	3	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:00

S143	68	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:01
S144	24	locat\$3 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:01
S145	13	locat\$3 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:02
S146	23	type with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer same (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:04
S147	18	type with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:05
S148	18	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type with underlayer with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:05
S149	8	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (site or position or location) with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:07
S150	8	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (site or position or location) same (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:08

S151	19	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (site or position or locat\$3) same (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:09
S152	19	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with underlayer with (site or position or locat\$3) with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:09
S153	17	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and underlayer with (site or position or locat\$3) with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:11
S154	18	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and underlayer with (site or position or locat\$3) with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:11
S155	18	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with underlayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:13
S156	101	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or low\$3 adj layer or underlayer) not S155	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:19
S157	6	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with cause with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or low\$3 adj layer or underlayer) not S155	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:22

S158	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with cause with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer) not S155	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:22
S159	112	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer) not S155	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:24
S160	10	cause with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer) not S155	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/11 18:24
S161	1	point adj scan with depth adj profile same chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 13:29
S162	224	702/59.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 13:48
S163	528	702/65.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 14:14
S164	789	702/185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 14:15
S165	555	702/181.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 14:15

S166	380	702/155.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:17
S167	514	702/81.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:18
S168	527	702/84.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:18
S170	956	714/736.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:18
S171	100	714/737.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:19
S172	306	714/732.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:19
S173	3848	714/724.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:19
S174	1284	714/763.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:19

S175	1668	714/726.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:20
S176	580	714/727.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:20
S177	161	714/728.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:26
S178	956	714/736.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:26
S179	100	714/737.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:26
S180	1539	714/738.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:26
S181	3492	714/718.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:26
S182	423	714/723.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:30

S183	1875	257/e21.525.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:30
S184	1757	257/751.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:47
S185	556	257/752.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:47
S186	3202	257/774.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:47
S187	1140	324/763.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:48
S188	5689	324/765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:48
S189	2137	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:53
S190	454	700/109.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:53

S191	619	700/110.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:56
S192	723	700/95.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:56
S193	1195	700/117.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:56
S194	2137	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:58
S195	2739	438/14.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 17:58
S196	759	382/149.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 18:00
S197	4124	365/201.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 18:00
S198	1	scan with analy\$4 same delayer with analy\$4 same depth with profile with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 18:04

S199	1	scan with analy\$4 same delayer with analy\$4 and depth with profile with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 18:05
S200	1	scan with analy\$4 and delayer with analy\$4 and depth with profile with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 18:05
S201	3	scan with analy\$4 and delay\$3 with analy\$4 and depth with profile with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 18:05
S202	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point with scan or delayer or depth with profile) with analysis and chemical\$2 with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 20:27
S203	34	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (scan or delay\$3 or depth with profile) with analy\$4 and chemical\$2 with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 20:28
S204	25	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (scan or delay\$3 or depth with profile) with analy\$4 same chemical\$2 with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 20:28
S205	6	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (scan or delay\$3 or depth with profile) with analy\$4 with chemical\$2 with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 20:28
S206	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and chemical\$2 with analy\$4 with "0.2"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 20:29

S207	5	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and chemical\$2 with analy\$4 with "0.2"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/15 20:30
S208	2	("5847821").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/15 20:34
S209	8	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and locat\$3 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayeror or under adj layer or lower-layer or lowerlayer or lower adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 09:37
S211	31	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayeror or under adj layer or lower-layer or lowerlayer or lower adj layer) with (locat\$3 or position or site or area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 09:48
S212	15	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayeror or under adj layer or lower-layer or lowerlayer or lower adj layer) with (locat\$3 or position or site or area) and (classify\$4 or classification or class or categor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 09:52
S213	12	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayeror or under1 adj layer or lower-layer or lowerlayer or lower adj layer) with (locat\$3 or position or site or area) and (classify\$4 or classification or class or categor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 09:55

S214	15	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal \$5) with (under-layer or underlayeror or under adj1 layer or lower-layer or lowerlayer or lower adj layer) with (locat\$3 or position or site or area) and (classify\$4 or classification or class or categor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 09:55
S215	0	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal \$5) with located with (under-layer or underlayeror or under adj1 layer or lower-layer or lowerlayer or lower adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:13
S216	14	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with located with (under-layer or underlayeror or under adj1 layer or lower-layer or lowerlayer or lower adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:14
S217	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with located with (under-layer or underlayeror or under adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:28
S218	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (posit\$4 or locat\$4) with (under-layer or underlayeror or under adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:29
S219	31	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayeror or under adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:30
S220	158	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:34

S221	26	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:34
S222	9	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayer or under adj layer) with (locat\$3 or position or site or area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:48
S223	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayer or under adj layer) with (locat\$3 or position or site or area) and chemical\$2 with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:57
S224	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayer or under adj layer) with (locat\$3 or position or site or area) and chemical\$2 with analy\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 10:58
S225	6	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayer or under adj layer) with (locat\$3 or position or site or area) and (FIB or SAM or AES or EDS)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:00
S226	0	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj layer) with (locat\$3 or position or site or area) and (FIB or SAM or AES or EDS) and (classify\$4 or classification or class or categor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:05
S227	0	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj layer) and (FIB or SAM or AES or EDS) and (classify\$4 or classification or class or categor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:06

S228	7	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj layer) and (classify\$4 or classification or class or categor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:06
S229	1	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (energy dispersive spectrometer or EDS) with ("0.1" or "0.2" or "0.3") and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:21
S230	312	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (energy dispersive spectrometer or EDS) with ("0.1" or "0.2" or "0.3")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:21
S231	3	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (energy dispersive spectrometer or EDS) with ("0.1" or "0.2" or "0.3") and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayer or under adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 11:22
S232	52	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (under-layer or underlayer or under adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 12:57
S233	14	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) near (under-layer or underlayer or under adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 12:57
S234	16	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5 or loss) near (under-layer or underlayer or under adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 13:05

S235	2	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5 or loss) near (under-layer or underlayer or under adj layer) not S233	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 13:10
S236	159	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5 or loss) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj layer) not S233	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 13:16
S237	22	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5 or loss) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or underlayer or under adj layer) not S233	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 13:17
S238	39	(defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with cause with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5 or loss) with (under-layer or underlayer or under adj layer) not S233	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/16 13:23
S239	3	("6516433").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/21 17:12
S240	5624	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and semiconductor with fabricat\$3 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:18
S241	10	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and semiconductor with fabricat\$3 with process\$3 with chemical with (state or status or condition)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:19

S242	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (die or semiconductor or wafer or chip or IC or integrated adj circuit) with fabricat\$3 with process\$3 with chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3) not S241	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:26
S243	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (die or semiconductor or wafer or chip or IC or integrated adj circuit) with fabricat\$3 with process\$3 with chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:27
S244	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and fabricat\$3 with process\$3 with chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:27
S245	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and fabricat\$3 with process\$3 same chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:27
S246	1	(die or semiconductor or wafer or chip or IC or integrated adj circuit) with fabricat\$3 with process\$3 same chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:28
S247	5	(die or semiconductor or wafer or chip or IC or integrated adj circuit) and fabricat\$3 with process\$3 same chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 17:28

S248	184	(die or semiconductor or wafer or chip or IC or integrated adj circuit) and fabricat\$3 with process\$3 and chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 18:56
S249	6	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and semiconductor with fabricat\$3 with process\$3 and chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 18:58
S250	8	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (die or semiconductor or wafer or chip or IC or integrated adj circuit) with fabricat\$3 with process\$3 and chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 18:59
S251	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (die or semiconductor or wafer or chip or IC or integrated adj circuit) with fabricat\$3 with chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 18:59
S252	20	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (die or semiconductor or wafer or chip or IC or integrated adj circuit) with chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 18:59
S253	11	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (die or semiconductor or wafer or chip or IC or integrated adj circuit) with fabricat\$3 and chemical with (state or status or condiction) with (analysis or analyz\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:00

S254	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and poly-silicon with chemical with (state or status or condition) with (analysis or analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:06
S255	0	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (poly with silicon or poly-silicon) same chemical with (state or status or condition) with (analysis or analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:06
S256	1	(poly with silicon or poly-silicon) same chemical with (state or status or condition) with (analysis or analyz\$3 or analys\$3) with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:07
S257	1	(poly with silicon or poly-silicon) same chemical with (state or status or condition) with (analysis or analyz\$3 or analys\$3) same (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:08
S258	2	(poly with silicon or poly-silicon) same chemical with (state or status or condition) with (analysis or analyz\$3 or analys\$3) and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:08
S259	37	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with chemical with (component or element) with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:11
S260	1	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with chemical with (component or element) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and chemical with particle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:21

S261	1	(poly with silicon or poly-silicon or polysilicon) with particle with chemical with component with (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:37
S262	1	(poly with silicon or poly-silicon or polysilicon) with particle with chemical with (element or component) same (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:38
S263	2	(poly with silicon or poly-silicon or polysilicon) with particle with chemical with (element or component) and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:38
S264	0	lithography with etch with oxidation with process\$3 with chemical with (element or component) and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:45
S265	697	(lithography or etch or oxidation) with process\$3 with chemical with (element or component) and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:46
S266	2	(lithography or etch or oxidation) with process\$3 with chemical with (state or status or condition) with (analysis or analyz\$3 or analys\$3) and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:46
S267	478	(lithography or etch or oxidation) with process\$3 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with chemical and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:48
S268	12	(lithography or etch or oxidation) with process\$3 with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with chemical with (component or element) and (die or semiconductor or wafer or chip or IC or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 19:48

S269	25	(US-20050049836-\$ or US-20080129988-\$ or US-20080115029-\$ or US-20080081385-\$ or US-20050004774-\$ or US-20020196969-\$ or US-20040252879-\$ or US-20050159909-\$ or US-20050177264-\$ or US-20050080572-\$ or US-20040122859-\$).did. or (US-6516433-\$ or US-7337034-\$ or US-6466895-\$ or US-6407386-\$ or US-6392434-\$ or US-5787190-\$ or US-6971054-\$ or US-6777677-\$ or US-5985680-\$ or US-5991699-\$ or US-7020536-\$ or US-7071011-\$ or US-7359544-\$ or US-6744266-\$ or US-6734277-\$ or US-5561293-\$).did. or (US-6516433-B-\$ or US-5972728-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2008/12/21 21:53
S270	1	S269 and point with scan with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:53
S271	1	S269 and delayer with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:54
S272	1	S269 and depth with profile with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:54
S273	1	point with scan with analysis and delayer with analysis and depth with profile with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:55
S274	1	point with scan with depth with profile with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:55
S275	523	point with scan with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:55

S276	860	depth with profile with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:56
S277	1	point with scan and delayer with analysis and depth with profile	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:56
S279	1	point with scan with depth with profile with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 21:57
S280	244	702/59.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:12
S281	564	702/65.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:12
S282	842	702/185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:12
S283	604	702/181.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:13
S284	413	702/155.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14

S285	558	702/81.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14
S286	543	702/84.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14
S287	994	714/736.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14
S288	101	714/737.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14
S289	324	714/732.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14
S290	3963	714/724.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:14
S291	1337	714/763.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S292	1770	714/726.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15

S293	635	714/727.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S294	175	714/728.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S295	994	714/736.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S296	1600	714/738.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S297	3615	714/718.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S298	453	714/723.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:15
S299	1981	257/e21.525.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:16
S300	1890	257/751.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:17

S301	569	257/752.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:17
S302	3378	257/774.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:17
S303	1235	324/763.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:17
S304	5900	324/765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:17
S305	2251	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:18
S306	491	700/109.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:22
S307	665	700/110.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:25
S308	749	700/95.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:27

S309	1232	700/117.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:27
S310	2251	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:27
S311	2823	438/14.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:28
S312	805	382/149.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:28
S313	4326	365/201.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:28
S314	40947	702/59,65,185,181,155,81,84.ccls. or 714/736,737,732,724,763,726,727,728,738,718,723.ccls. or 257/ e21.525,751,752,774.ccls. or 324/763,765.ccls. or 700/121,109,110,95,117,121.ccls. or 438/14.ccls. or 382/149.ccls. or 365/201.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:31
S315	49	S314 and (determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:32
S316	20	S314 and (determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip)	US-PGPUB	OR	ON	2008/12/21 22:32

S317	50	S314 and (determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with root with (die or semiconductor or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:32
S318	10	S314 and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan\$4 with auger with microscopy) and focus\$3 with ion with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:33
S319	2	S314 and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (semiconductor or chip or wafer or IC or integrated adj circuit) and (auger with electron with spectroscopy or scan\$4 with auger with microscopy) and focus\$3 with ion with beam	US-PGPUB	OR	ON	2008/12/21 22:33
S320	17	S314 and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point with scan or delayer or depth with profile) with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:33
S321	11	S314 and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with type same (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point with scan or delayer or depth with profile) with analysis	US-PGPUB	OR	ON	2008/12/21 22:34
S322	3	S314 and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point adj scan or delayer or depth adj profile) same chemical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:34
S323	1	S314 and (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) and (point adj scan or delayer or depth adj profile) same chemical	US-PGPUB	OR	ON	2008/12/21 22:34
S324	20	(determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with underlayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:34

S325	23	S314 and (determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or low\$3 adj layer or underlayer) not S324	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/21 22:34
S326	7	S314 and (determin\$3 or monitor\$3 or indicat\$3 or detect\$3 or identif\$4 or sens\$3 or measur\$6 or inspect\$4) with (defect or fail\$3 or fault or anomaly or malfunction\$2 or error or problem or disorder or abnormal\$5) with (die or semiconductor or wafer or chip or IC or integrated adj circuit) with (under-layer or low\$3 adj layer or underlayer) not S324	US-PGPUB	OR	ON	2008/12/21 22:35

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